



# SOT146-5

DIP20, plastic, dual in-line package; 20 terminals; 2.54 mm pitch; 25.9 mm x 6.6 mm x 3.9 mm body

18 September 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	DIP20
<b>Package style descriptive code</b>	DIP (dual in-line package)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	08-08-2018
<b>Manufacturer package code</b>	98ASA01305D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	25.9	-	mm
package width	-	6.6	-	mm
package height	-	3.9	-	mm
nominal pitch	-	2.54	-	mm
actual quantity of termination	-	20	-	



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2 Package outline

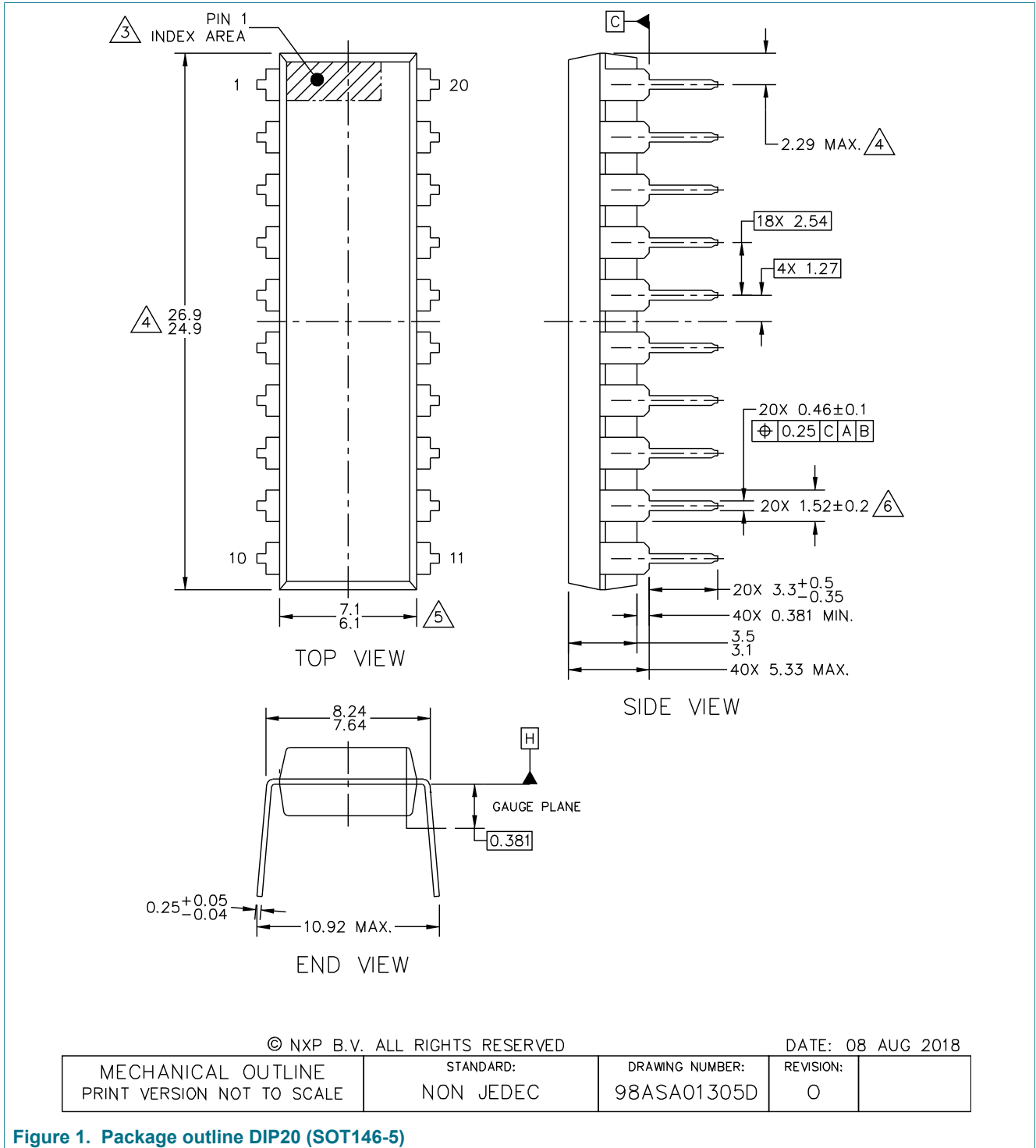


Figure 1. Package outline DIP20 (SOT146-5)

DIP20, plastic, dual in-line package; 20 terminals; 2.54 mm pitch; 25.9 mm x 6.6 mm x 3.9 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.15 PER END.
5. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR MOLD PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
6. DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION. DAM BAR PROTRUSION SHALL NOT EXCEED 0.25MM.

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DATE: 08 AUG 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01305D	REVISION: 0	
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Figure 2. Package outline note DIP20 (SOT146-5)

### 3 Legal information

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